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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

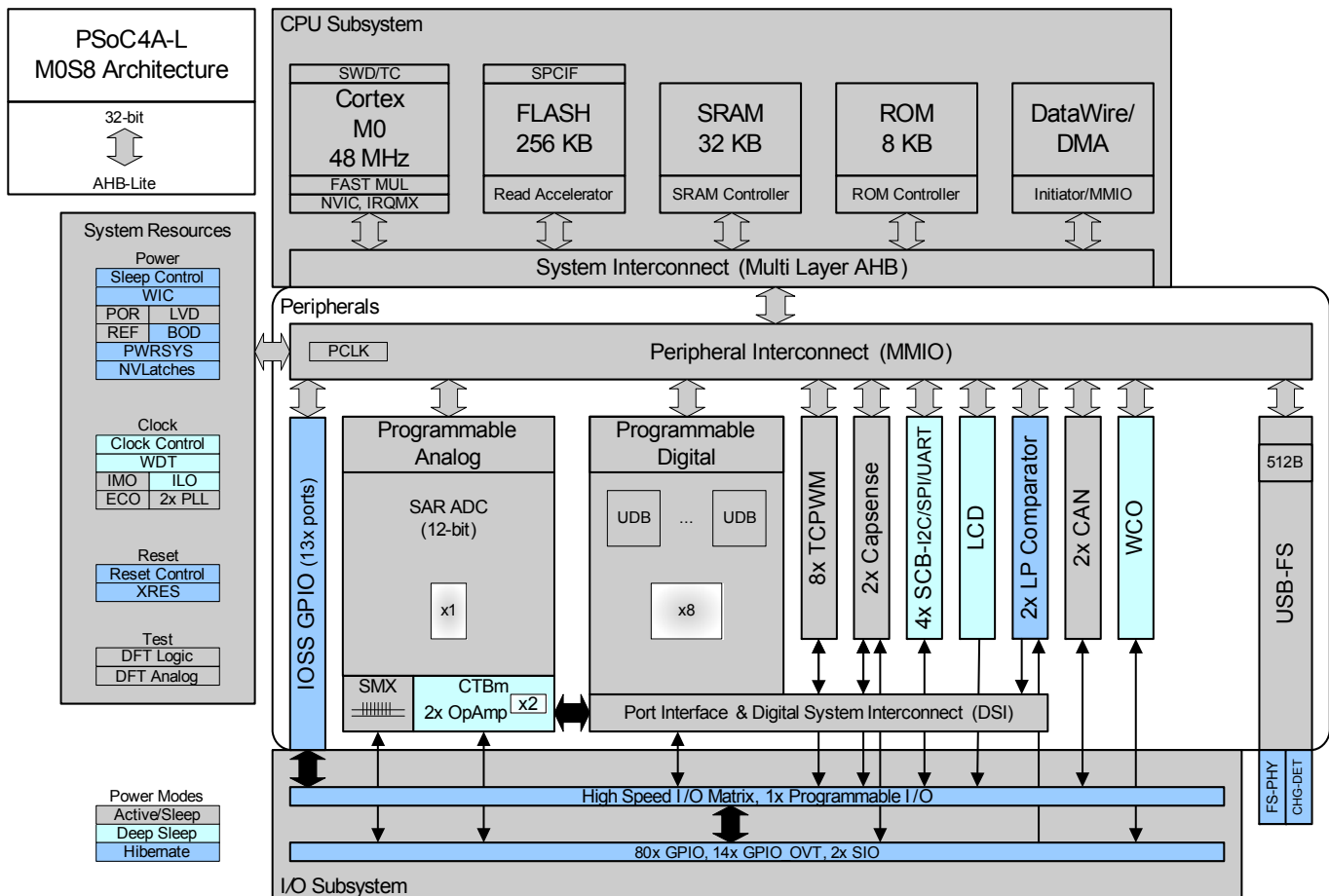
#### Details

Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I <sup>2</sup> C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART, USB
Peripherals	Brown-out Detect/Reset, Cap Sense, DMA, LVD, POR, PWM, SmartSense, WDT
Number of I/O	57
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 16x12b SAR; D/A 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	68-VFQFN Exposed Pad
Supplier Device Package	68-QFN (8x8)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4248lti-l475">https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4248lti-l475</a>

## Contents

<b>PSoC 4200-L Block Diagram .....</b>	<b>4</b>	Device Level Specifications.....	17
<b>Functional Definition.....</b>	<b>5</b>	Analog Peripherals .....	21
CPU and Memory Subsystem .....	5	Digital Peripherals .....	26
System Resources .....	5	Memory .....	29
Analog Blocks.....	6	System Resources .....	30
Programmable Digital .....	7	<b>Ordering Information.....</b>	<b>37</b>
Fixed Function Digital .....	8	Part Numbering Conventions .....	38
GPIO .....	9	<b>Packaging.....</b>	<b>39</b>
SIO .....	9	<b>Acronyms.....</b>	<b>42</b>
Special Function Peripherals.....	9	<b>Document Conventions .....</b>	<b>44</b>
<b>Pinouts .....</b>	<b>10</b>	Units of Measure .....	44
<b>Power.....</b>	<b>15</b>	<b>Revision History .....</b>	<b>45</b>
Unregulated External Supply.....	15	<b>Sales, Solutions, and Legal Information .....</b>	<b>46</b>
Regulated External Supply .....	15	Worldwide Sales and Design Support.....	46
<b>Development Support .....</b>	<b>16</b>	Products .....	46
Documentation .....	16	PSoC® Solutions .....	46
Online .....	16	Cypress Developer Community.....	46
Tools.....	16	Technical Support .....	46
<b>Electrical Specifications .....</b>	<b>17</b>		
Absolute Maximum Ratings.....	17		

**Figure 2. Block Diagram**



## PSoC 4200-L Block Diagram

The PSoC 4200-L devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The ARM Serial\_Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full-device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator Integrated Development Environment (IDE) provides fully integrated programming and debug support for PSoC 4200-L devices. The SWD interface is fully compatible with industry-standard third-party tools. The PSoC 4200-L family provides a level of security not possible with multi-chip application solutions or with microcontrollers. This is due to its ability

to disable debug features, robust flash protection, and because it allows customer-proprietary functionality to be implemented in on-chip programmable blocks.

The debug circuits are enabled by default and can only be disabled in firmware. If not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging.

Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. Because all programming, debug, and test interfaces are disabled when maximum device security is enabled, PSoC 4200-L with device security enabled may not be returned for failure analysis. This is a trade-off the PSoC 4200-L allows the customer to make.

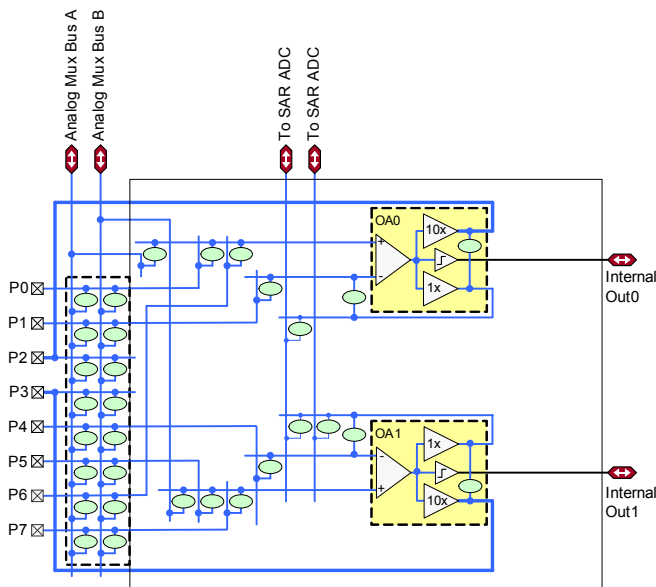
### Analog Multiplex Bus

The PSoC4200-L has two concentric analog buses (Analog Mux Bus A and Analog Mux Bus B) that circumnavigate the periphery of the chip. These buses can transport analog signals from any pin to various analog blocks (including the opamps) and to the CapSense blocks allowing, for instance, the ADC to monitor any pin on the chip. These buses are independent and can also be split into three independent sections. This allows one section to be used for CapSense purposes, one for general analog signal processing, and the third for general-purpose digital peripherals and GPIO.

### Four Opamps (CTBm Blocks)

The PSoC 4200-L has four opamps with Comparator modes, which allow most common analog functions to be performed on-chip eliminating external components; PGAs, voltage buffers, filters, trans-impedance amplifiers, and other functions can be realized with external passives saving power, cost, and space. The on-chip opamps are designed with enough bandwidth to drive the Sample-and-Hold circuit of the ADC without requiring external buffering. The opamps can operate in the Deep Sleep mode at very low power levels. The following diagram shows one of two identical opamp pairs of the opamp subsystem.

**Figure 5. Identical Opamp Pairs in Opamp Subsystem**



The ovals in Figure 5 represent analog switches, which may be controlled via user firmware, the SAR sequencer, or user-defined programmable logic. The opamps (OA0 and OA1) are configurable via these switches to perform all standard opamp functions with appropriate feedback components.

The opamps (OA0 and OA1) are programmable and reconfigurable to provide standard opamp functionality via switchable feedback components, unity gain functionality for driving pins directly, or for internal use (such as buffering SAR ADC inputs as indicated in the diagram), or as true comparators.

The opamp inputs provide highly flexible connectivity and can connect directly to dedicated pins or, via the analog mux buses,

to any pin on the chip. Analog switch connectivity is controllable by user firmware as well as user-defined programmable digital state machines (implemented via UDBs).

The opamps operate in Deep Sleep mode at very low currents allowing analog circuits to remain operational during Deep Sleep.

### Temperature Sensor

The PSoC 4200-L has one on-chip temperature sensor. This consists of a diode, which is biased by a current source that can be disabled to save power. The temperature sensor is connected to the ADC, which digitizes the reading and produces a temperature value using Cypress-supplied software that includes calibration and linearization.

### Low-power Comparators

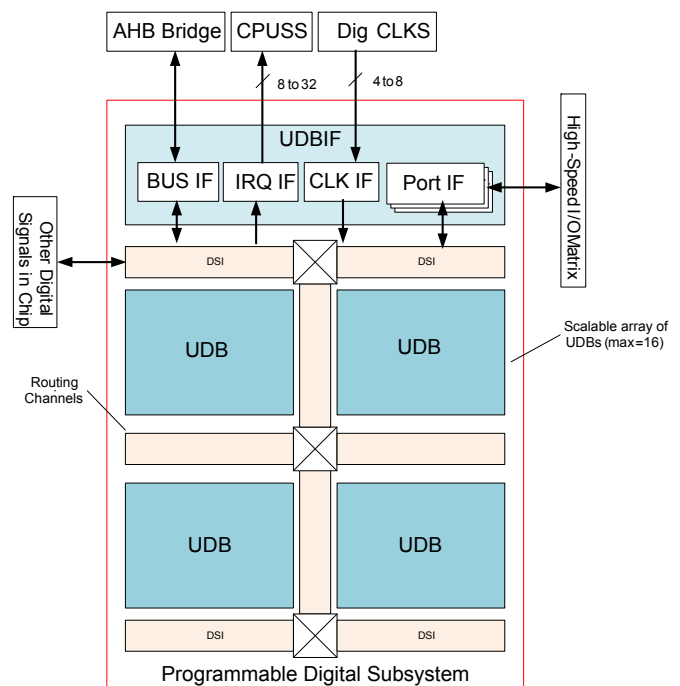
The PSoC 4200-L has a pair of low-power comparators, which can also operate in the Deep Sleep and Hibernate modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid meta-stability unless operating in an asynchronous power mode (Hibernate) where the system wake-up circuit is activated by a comparator switch event.

## Programmable Digital

### Universal Digital Blocks (UDBs) and Port Interfaces

The PSoC 4200-L has eight UDBs; the UDB array also provides a switched Digital System Interconnect (DSI) fabric that allows signals from peripherals and ports to be routed to and through the UDBs for communication and control. The UDB array is shown in the following figure.

**Figure 6. UDB Array**



## Pinouts

The following is the pin list for the PSoC 4200-L.

124-BGA		68-QFN		64-TQFP		48-TQFP		48-TQFP-USB	
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name
H13	P0.0	42	P0.0	39	P0.0	28	P0.0	28	P0.0
H12	P0.1	43	P0.1	40	P0.1	29	P0.1	29	P0.1
G13	P0.2	44	P0.2	41	P0.2	30	P0.2	30	P0.2
G12	P0.3	45	P0.3	42	P0.3	31	P0.3	31	P0.3
K10	VSSD								
G11	P0.4	46	P0.4	43	P0.4	32	P0.4	32	P0.4
F13	P0.5	47	P0.5	44	P0.5	33	P0.5	33	P0.5
F12	P0.6	48	P0.6	45	P0.6	34	P0.6	34	P0.6
F11	P0.7	49	P0.7	46	P0.7	35	P0.7	35	P0.7
E13	P8.0								
E12	P8.1								
E11	P8.2								
D13	P8.3								
D12	P8.4								
C13	P8.5								
C12	P8.6								
B12	P8.7								
C11	XRES	50	XRES	47	XRES	36	XRES	36	XRES
A12	VCCD	51	VCCD	48	VCCD	37	VCCD	37	VCCD
D10	VSSD	52	VSSD	49	VSSD	38	VSSD	38	VSSD
B13	VDDD	53	VDDD	50	VDDD	39	VDDD	39	VDDD
A13	VDDD	53	VDDD	50	VDDD	39	VDDD	39	VDDD
A11	P9.0								
B11	P9.1								
A10	P9.2								
B10	P9.3								
C10	P9.4								
A9	P9.5								
B9	P9.6								
C9	P9.7								
						40	VDDA	40	VDDA
C8	P5.0	54	P5.0	51	P5.0				
B8	P5.1	55	P5.1	52	P5.1				
A8	P5.2	56	P5.2	53	P5.2				
A7	P5.3	57	P5.3	54	P5.3				
B7	P5.4	58	P5.4						
C7	P5.5	59	P5.5	55	P5.5				
A6	P5.6								
B6	P5.7								
A2	VDDA	60	VDDA	56	VDDA	40	VDDA	40	VDDA
B2	VDDA	60	VDDA	56	VDDA	40	VDDA	40	VDDA

## Development Support

The PSoC 4200-L family has a rich set of documentation, development tools, and online resources to assist you during your development process. Visit [www.cypress.com/go/psoc4](http://www.cypress.com/go/psoc4) to find out more.

### Documentation

A suite of documentation supports the PSoC 4200-L family to ensure that you can find answers to your questions quickly. This section contains a list of some of the key documents.

**Software User Guide:** A step-by-step guide for using PSoC Creator. The software user guide shows you how the PSoC Creator build process works in detail, how to use source control with PSoC Creator, and much more.

**Component Datasheets:** The flexibility of PSoC allows the creation of new peripherals (components) long after the device has gone into production. Component data sheets provide all of the information needed to select and use a particular component, including a functional description, API documentation, example code, and AC/DC specifications.

**Application Notes:** PSoC application notes discuss a particular application of PSoC in depth; examples include brushless DC motor control and on-chip filtering. Application notes often include example projects in addition to the application note document.

**Technical Reference Manual:** The Technical Reference Manual (TRM) contains all the technical detail you need to use a PSoC device, including a complete description of all PSoC registers.

### Online

In addition to print documentation, the Cypress PSoC forums connect you with fellow PSoC users and experts in PSoC from around the world, 24 hours a day, 7 days a week.

### Tools

With industry standard cores, programming, and debugging interfaces, the PSoC 4200-L family is part of a development tool ecosystem. Visit us at [www.cypress.com/go/psoccreator](http://www.cypress.com/go/psoccreator) for the latest information on the revolutionary, easy to use PSoC Creator IDE, supported third party compilers, programmers, debuggers, and development kits.

**Table 2. DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID23	I <sub>DD18</sub>	I <sup>2</sup> C wakeup, WDT, and Comparators on. Regulator Off.	–	2.4	2.9	mA	V <sub>DD</sub> = 1.71 to 1.89, 12 MHz
SID24	I <sub>DD19</sub>	I <sup>2</sup> C wakeup, WDT, and Comparators on.	–	2.3	2.8	mA	V <sub>DD</sub> = 1.8 to 5.5, 12 MHz
<b>Deep Sleep Mode, –40 °C to + 60 °C</b>							
SID30	I <sub>DD25</sub>	I <sup>2</sup> C wakeup and WDT on. Regulator Off.	–	–	13.5	μA	V <sub>DD</sub> = 1.71 to 1.89
SID31	I <sub>DD26</sub>	I <sup>2</sup> C wakeup and WDT on.	–	1.3	20.0	μA	V <sub>DD</sub> = 1.8 to 3.6
SID32	I <sub>DD27</sub>	I <sup>2</sup> C wakeup and WDT on.	–	–	20.0	μA	V <sub>DD</sub> = 3.6 to 5.5
<b>Deep Sleep Mode, +85 °C</b>							
SID33	I <sub>DD28</sub>	I <sup>2</sup> C wakeup and WDT on. Regulator Off.	–	–	45.0	μA	V <sub>DD</sub> = 1.71 to 1.89
SID34	I <sub>DD29</sub>	I <sup>2</sup> C wakeup and WDT on.	–	15	60.0	μA	V <sub>DD</sub> = 1.8 to 3.6
SID35	I <sub>DD30</sub>	I <sup>2</sup> C wakeup and WDT on.	–	–	45.0	μA	V <sub>DD</sub> = 3.6 to 5.5
<b>Hibernate Mode, –40 °C to + 60 °C</b>							
SID39	I <sub>DD34</sub>	Regulator Off.	–	–	1123	nA	V <sub>DD</sub> = 1.71 to 1.89
SID40	I <sub>DD35</sub>		–	150	1600	nA	V <sub>DD</sub> = 1.8 to 3.6
SID41	I <sub>DD36</sub>		–	–	1600	nA	V <sub>DD</sub> = 3.6 to 5.5
<b>Hibernate Mode, +85 °C</b>							
SID42	I <sub>DD37</sub>	Regulator Off.	–	–	4142	nA	V <sub>DD</sub> = 1.71 to 1.89
SID43	I <sub>DD38</sub>		–	–	9700	nA	V <sub>DD</sub> = 1.8 to 3.6
SID44	I <sub>DD39</sub>		–	–	10,400	nA	V <sub>DD</sub> = 3.6 to 5.5
<b>Stop Mode</b>							
SID304	I <sub>DD43A</sub>	Stop Mode current; V <sub>DD</sub> = 3.6 V	–	20	659	nA	T = –40 °C to +60 °C
SID304A	I <sub>DD43B</sub>	Stop Mode current; V <sub>DD</sub> = 3.6 V	–	–	1810	nA	T = +85 °C
<b>XRES current</b>							
SID307	I <sub>DD_XR</sub>	Supply current while XRES (Active Low) asserted	–	2	5	mA	

**Table 3. AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID48	F <sub>CPU</sub>	CPU frequency	DC	–	48	MHz	1.71 ≤ V <sub>DD</sub> ≤ 5.5
SID49	T <sub>SLEEP</sub>	Wakeup from sleep mode	–	0	–	μs	Guaranteed by characterization
SID50	T <sub>DEEPSLEEP</sub>	Wakeup from Deep Sleep mode	–	–	25	μs	24-MHz IMO. Guaranteed by characterization
SID51	T <sub>HIBERNATE</sub>	Wakeup from Hibernate mode	–	–	0.7	ms	Guaranteed by characterization
SID51A	T <sub>STOP</sub>	Wakeup from Stop mode	–	–	1.9	ms	Guaranteed by characterization
SID52	T <sub>RESETWIDTH</sub>	External reset pulse width	1	–	–	μs	Guaranteed by characterization

**Table 5. GPIO AC Specifications**

 (Guaranteed by Characterization)<sup>[3]</sup>

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID70	T <sub>RISEF</sub>	Rise time in fast strong mode	2	–	12	ns	3.3 V V <sub>DDD</sub> , Cload = 25 pF
SID71	T <sub>FALLF</sub>	Fall time in fast strong mode	2	–	12	ns	3.3 V V <sub>DDD</sub> , Cload = 25 pF
SID72	T <sub>RISES</sub>	Rise time in slow strong mode	10	–	60	ns	3.3 V V <sub>DDD</sub> , Cload = 25 pF
SID73	T <sub>FALLS</sub>	Fall time in slow strong mode	10	–	60	ns	3.3 V V <sub>DDD</sub> , Cload = 25 pF
SID74	F <sub>GPIOOUT1</sub>	GPIO Fout; 3.3 V ≤ V <sub>DDD</sub> ≤ 5.5 V. Fast strong mode.	–	–	33	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID75	F <sub>GPIOOUT2</sub>	GPIO Fout; 1.7 V ≤ V <sub>DDD</sub> ≤ 3.3 V. Fast strong mode.	–	–	16.7	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID76	F <sub>GPIOOUT3</sub>	GPIO Fout; 3.3 V ≤ V <sub>DDD</sub> ≤ 5.5 V. Slow strong mode.	–	–	7	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID245	F <sub>GPIOOUT4</sub>	GPIO Fout; 1.7 V ≤ V <sub>DDD</sub> ≤ 3.3 V. Slow strong mode.	–	–	3.5	MHz	90/10%, 25 pF load, 60/40 duty cycle
SID246	F <sub>GPIOIN</sub>	GPIO input operating frequency; 1.71 V ≤ V <sub>DDD</sub> ≤ 5.5 V	–	–	48	MHz	90/10% V <sub>IO</sub>

#### XRES

**Table 6. XRES DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID77	V <sub>IH</sub>	Input voltage high threshold	0.7 × V <sub>DDD</sub>	–	–	V	CMOS Input
SID78	V <sub>IL</sub>	Input voltage low threshold	–	–	0.3 × V <sub>DDD</sub>	V	CMOS Input
SID79	R <sub>PULLUP</sub>	Pull-up resistor	3.5	5.6	8.5	kΩ	
SID80	C <sub>IN</sub>	Input capacitance	–	3	–	pF	
SID81	V <sub>HYSXRES</sub>	Input voltage hysteresis	–	100	–	mV	Guaranteed by characterization
SID82	I <sub>DIODE</sub>	Current through protection diode to V <sub>DDD</sub> /V <sub>SS</sub>	–	–	100	μA	Guaranteed by characterization

**Table 7. XRES AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/ Conditions
SID83	T <sub>RESETWIDTH</sub>	Reset pulse width	1	–	–	μs	Guaranteed by characterization

**Note**

3. Simultaneous switching transitions on many fully-loaded GPIO pins may cause ground perturbations depending on several factors including PCB and decoupling capacitor design. For applications that are very sensitive to ground perturbations, the slower GPIO slew rate setting may be used.



**Table 8. Opamp Specifications**

(Guaranteed by Characterization) (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID295	V <sub>N3</sub>	Input referred, 10kHz, power = high	–	28	–	nV/rtHz	
SID296	V <sub>N4</sub>	Input referred, 100kHz, power = high	–	15	–	nV/rtHz	
SID297	Cload	Stable up to maximum load. Performance specs at 50 pF.	–	–	125	pF	
SID298	Slew_rate	Cload = 50 pF, Power = High, V <sub>DDA</sub> ≥ 2.7 V	6	–	–	V/μs	
SID299	T <sub>op_wake</sub>	From disable to enable, no external RC dominating	–	25	–	μs	
SID299A	OL_GAIN	Open Loop Gain	–	90	–	dB	
	Comp_mode	Comparator mode; 50 mV drive, T <sub>rise</sub> = T <sub>fall</sub> (approx.)	–	–	–		
SID300	T <sub>PD1</sub>	Response time; power = high	–	150	–	ns	
SID301	T <sub>PD2</sub>	Response time; power = medium	–	400	–	ns	
SID302	T <sub>PD3</sub>	Response time; power = low	–	2000	–	ns	
SID303	V <sub>hyst_op</sub>	Hysteresis	–	10	–	mV	
<b>Deep Sleep Mode</b>		Mode 2 is lowest current range. Mode 1 has higher GBW.					Deep Sleep mode V <sub>DDA</sub> ≥ 2.7 V.
SID_DS_1	IDD_HI_M1	Mode 1, High current	–	1400	–	μA	25 °C
SID_DS_2	IDD_MED_M1	Mode 1, Medium current	–	700	–	μA	25 °C
SID_DS_3	IDD_LOW_M1	Mode 1, Low current	–	200	–	μA	25 °C
SID_DS_4	IDD_HI_M2	Mode 2, High current	–	120	–	μA	25 °C
SID_DS_5	IDD_MED_M2	Mode 2, Medium current	–	60	–	μA	25 °C
SID_DS_6	IDD_LOW_M2	Mode 2, Low current	–	15	–	μA	25 °C
SID_DS_7	GBW_HI_M1	Mode 1, High current	–	4	–	MHz	20-pF load, no DC load 0.2 V to V <sub>DDA</sub> -1.5 V
SID_DS_8	GBW_MED_M1	Mode 1, Medium current	–	2	–	MHz	20-pF load, no DC load 0.2 V to V <sub>DDA</sub> -1.5 V
SID_DS_9	GBW_LOW_M1	Mode 1, Low current	–	0.5	–	MHz	20-pF load, no DC load 0.2 V to V <sub>DDA</sub> -1.5 V
SID_DS_10	GBW_HI_M2	Mode 2, High current	–	0.5	–	MHz	20-pF load, no DC load 0.2 V to V <sub>DDA</sub> -1.5 V
SID_DS_11	GBW_MED_M2	Mode 2, Medium current	–	0.2	–	MHz	20-pF load, no DC load 0.2 V to V <sub>DDA</sub> -1.5 V
SID_DS_12	GBW_LOW_M2	Mode 2, Low current	–	0.1	–	MHz	20-pF load, no DC load 0.2 V to V <sub>DDA</sub> -1.5 V
SID_DS_13	VOS_HI_M1	Mode 1, High current	–	5	–	mV	With trim 25 °C, 0.2 V to V <sub>DDA</sub> -1.5 V
SID_DS_14	VOS_MED_M1	Mode 1, Medium current	–	5	–	mV	With trim 25 °C, 0.2 V to V <sub>DDA</sub> -1.5 V
SID_DS_15	VOS_LOW_M2	Mode 1, Low current	–	5	–	mV	With trim 25 °C, 0.2 V to V <sub>DDA</sub> -1.5 V
SID_DS_16	VOS_HI_M2	Mode 2, High current	–	5	–	mV	With trim 25 °C, 0.2 V to V <sub>DDA</sub> -1.5 V
SID_DS_17	VOS_MED_M2	Mode 2, Medium current	–	5	–	mV	With trim 25 °C, 0.2 V to V <sub>DDA</sub> -1.5 V

**Table 8. Opamp Specifications**

(Guaranteed by Characterization) (continued)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID_DS_18	VOS_LOW_M2	Mode 2, Low current	–	5	–	mV	With trim 25 °C, 0.2 V to $V_{DDA}-1.5$ V
SID_DS_19	IOOUT_HI_M1	Mode 1, High current	–	10	–	mA	Output is 0.5 V to $V_{DDA}-0.5$ V
SID_DS_20	IOOUT_MED_M1	Mode 1, Medium current	–	10	–	mA	Output is 0.5 V to $V_{DDA}-0.5$ V
SID_DS_21	IOOUT_LOW_M1	Mode 1, Low current	–	4	–	mA	Output is 0.5 V to $V_{DDA}-0.5$ V
SID_DS_22	IOOUT_HI_M2	Mode 2, High current	–	1	–	mA	Output is 0.5 V to $V_{DDA}-0.5$ V
SID_DS_23	IOU_MED_M2	Mode 2, Medium current	–	1	–	mA	Output is 0.5 V to $V_{DDA}-0.5$ V
SID_DS_24	IOU_LOW_M2	Mode 2, Low current	–	0.5	–	mA	Output is 0.5 V to $V_{DDA}-0.5$ V

#### Comparator

**Table 9. Comparator DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID85	$V_{OFFSET2}$	Input offset voltage. Custom trim. Common mode voltage range from 0 to $V_{DD}-1$ .	–	–	$\pm 4$	mV	
SID85A	$V_{OFFSET3}$	Input offset voltage. Ultra low-power mode.	–	$\pm 12$	–	mV	$V_{DDD} \geq 2.2$ V for Temp < 0 °C, $V_{DDD} \geq 1.8$ V for Temp > 0 °C
SID86	$V_{HYST}$	Hysteresis when enabled. Common mode voltage range from 0 to $V_{DD}-1$ .	–	10	35	mV	Guaranteed by characterization
SID87	$V_{ICM1}$	Input common mode voltage in normal mode	0	–	$V_{DDD}-0.2$	V	Modes 1 and 2.
SID247	$V_{ICM2}$	Input common mode voltage in low power mode	0	–	$V_{DDD}$	V	
SID247A	$V_{ICM2}$	Input common mode voltage in ultra low power mode	0	–	$V_{DDD}-1.15$	V	$V_{DDD} \geq 2.2$ V for Temp < 0 °C, $V_{DDD} \geq 1.8$ V for Temp > 0 °C
SID88	CMRR	Common mode rejection ratio	50	–	–	dB	$V_{DDD} \geq 2.7$ V. Guaranteed by characterization
SID88A	CMRR	Common mode rejection ratio	42	–	–	dB	$V_{DDD} < 2.7$ V. Guaranteed by characterization
SID89	$I_{CMP1}$	Block current, normal mode	–	280	400	$\mu$ A	Guaranteed by characterization
SID248	$I_{CMP2}$	Block current, low power mode	–	50	100	$\mu$ A	Guaranteed by characterization
SID259	$I_{CMP3}$	Block current, ultra low power mode	–	6	28	$\mu$ A	Guaranteed by characterization, $V_{DDD} \geq 2.2$ V for Temp < 0 °C, $V_{DDD} \geq 1.8$ V for Temp > 0 °C
SID90	$Z_{CMP}$	DC input impedance of comparator	35	–	–	M $\Omega$	Guaranteed by characterization

*LCD Direct Drive*

**Table 18. LCD Direct Drive DC Specifications**

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID154	I <sub>LCDLOW</sub>	Operating current in low power mode	–	5	–	μA	16 × 4 small segment disp. at 50 Hz
SID155	C <sub>LCDCAP</sub>	LCD capacitance per segment/common driver	–	500	5000	pF	Guaranteed by Design
SID156	LCD <sub>OFFSET</sub>	Long-term segment offset	–	20	–	mV	
SID157	I <sub>LCDOP1</sub>	PWM Mode current. 5-V bias. 24-MHz IMO	–	0.6	–	mA	32 × 4 segments. 50 Hz, 25 °C
SID158	I <sub>LCDOP2</sub>	PWM Mode current. 3.3-V bias. 24-MHz IMO.	–	0.5	–	mA	32 × 4 segments. 50 Hz, 25 °C

**Table 19. LCD Direct Drive AC Specifications**

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID159	F <sub>LCD</sub>	LCD frame rate	10	50	150	Hz	

**Table 20. Fixed UART DC Specifications**

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID160	I <sub>UART1</sub>	Block current consumption at 100 Kbits/sec	–	9	55	μA	
SID161	I <sub>UART2</sub>	Block current consumption at 1000 Kbits/sec	–	–	312	μA	

**Table 21. Fixed UART AC Specifications**

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID162	F <sub>UART</sub>	Bit rate	–	–	1	Mbps	

*SWD Interface*

**Table 32. SWD Interface Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID213	F_SWCLK1	$3.3\text{ V} \leq V_{DD} \leq 5.5\text{ V}$	–	–	14	MHz	SWDCLK $\leq$ 1/3 CPU clock frequency
SID214	F_SWCLK2	$1.71\text{ V} \leq V_{DD} \leq 3.3\text{ V}$	–	–	7	MHz	SWDCLK $\leq$ 1/3 CPU clock frequency
SID215	T_SWDI_SETUP	$T = 1/f\text{ SWDCLK}$	$0.25 \cdot T$	–	–	ns	Guaranteed by characterization
SID216	T_SWDI_HOLD	$T = 1/f\text{ SWDCLK}$	$0.25 \cdot T$	–	–	ns	Guaranteed by characterization
SID217	T_SWDO_VALID	$T = 1/f\text{ SWDCLK}$	–	–	$0.5 \cdot T$	ns	Guaranteed by characterization
SID217A	T_SWDO_HOLD	$T = 1/f\text{ SWDCLK}$	1	–	–	ns	Guaranteed by characterization

*Internal Main Oscillator*

**Table 33. IMO DC Specifications**

(Guaranteed by Design)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID218	I_IMO1	IMO operating current at 48 MHz	–	–	1000	μA	
SID219	I_IMO2	IMO operating current at 24 MHz	–	–	325	μA	
SID220	I_IMO3	IMO operating current at 12 MHz	–	–	225	μA	
SID221	I_IMO4	IMO operating current at 6 MHz	–	–	180	μA	
SID222	I_IMO5	IMO operating current at 3 MHz	–	–	150	μA	

**Table 34. IMO AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID223	F_IMOTOL1	Frequency variation from 3 to 48 MHz	–	–	$\pm 2$	%	
SID226	T_STARTIMO	IMO startup time	–	–	12	μs	
SID227	T_JITRMSIMO1	RMS Jitter at 3 MHz	–	156	–	ps	
SID228	T_JITRMSIMO2	RMS Jitter at 24 MHz	–	145	–	ps	
SID229	T_JITRMSIMO3	RMS Jitter at 48 MHz	–	139	–	ps	

*Internal Low-Speed Oscillator*

**Table 35. ILO DC Specifications**

(Guaranteed by Design)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID231	I_ILO1	ILO operating current at 32 kHz	–	0.3	1.05	μA	Guaranteed by Characterization
SID233	I_ILOLEAK	ILO leakage current	–	2	15	nA	Guaranteed by Design

**Table 36. ILO AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID234	T <sub>STARTILO1</sub>	ILO startup time	–	–	2	ms	Guaranteed by characterization
SID236	T <sub>ILODUTY</sub>	ILO duty cycle	40	50	60	%	Guaranteed by characterization
SID237	F <sub>ILOTRIM1</sub>	32 kHz trimmed frequency	15	32	50	kHz	±60% with trim.

**Table 37. PLL DC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID410	IDD_PLL_48	In = 3 MHz, Out = 48 MHz	–	530	610	µA	
SID411	IDD_PLL_24	In = 3 MHz, Out = 24 MHz	–	300	405	µA	

**Table 38. PLL AC Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID412	F <sub>PLLIN</sub>	PLL input frequency	1	–	48	MHz	
SID413	F <sub>PLLINT</sub>	PLL intermediate frequency; prescaler out	1	–	3	MHz	
SID414	F <sub>PLLVCO</sub>	VCO output frequency before post-divide	22.5	–	104	MHz	
SID415	D <sub>IVVCO</sub>	VCO Output post-divider range; PLL output frequency is F <sub>PLLVCO</sub> /D <sub>IVVCO</sub>	1	–	8	–	
SID416	PLLlocktime	Lock time at startup	–	–	250	µs	
SID417	Jperiod_1	Period jitter for VCO ≥ 67 MHz	–	–	150	ps	Guaranteed By Design
SID416A	Jperiod_2	Period jitter for VCO ≤ 67 MHz	–	–	200	ps	Guaranteed By Design

**Table 39. External Clock Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID305	ExtClkFreq	External Clock input Frequency	0	–	48	MHz	Guaranteed by characterization
SID306	ExtClkDuty	Duty cycle; Measured at V <sub>DD/2</sub>	45	–	55	%	Guaranteed by characterization

**Table 40. Watch Crystal Oscillator (WCO) Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>IMO WCO-PLL calibrated mode</b>							
SID330	IMOWCO1	Frequency variation with IMO set to 3 MHz	–0.6	–	0.6	%	Does not include WCO tolerance
SID331	IMOWCO2	Frequency variation with IMO set to 5 MHz	–0.4	–	0.4	%	Does not include WCO tolerance
SID332	IMOWCO3	Frequency variation with IMO set to 7 or 9 MHz	–0.3	–	0.3	%	Does not include WCO tolerance
SID333	IMOWCO4	All other IMO frequency settings	–0.2	–	0.2	%	Does not include WCO tolerance

**Table 40. Watch Crystal Oscillator (WCO) Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>WCO Specifications</b>							
SID398	FWCO	Crystal frequency	–	32.768	–	kHz	
SID399	FTOL	Frequency tolerance	–	50	250	ppm	With 20-ppm crystal.
SID400	ESR	Equivalent series resistance	–	50	–	kΩ	
SID401	PD	Drive Level	–	–	1	μW	
SID402	TSTART	Startup time	–	–	500	ms	
SID403	CL	Crystal load capacitance	6	–	12.5	pF	
SID404	C0	Crystal shunt capacitance	–	1.35	–	pF	
SID405	IWCO1	Operating current (high power mode)	–	–	8	uA	

**Table 41. External Crystal Oscillator (ECO) Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
SID316	IECO1	Block operating current	–	–	1.5	mA	
SID317	FECO	Crystal frequency range	4	–	33	MHz	

**Table 42. UDB AC Specifications**

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details/Conditions
<b>Datapath performance</b>							
SID249	F <sub>MAX-TIMER</sub>	Max frequency of 16-bit timer in a UDB pair	–	–	48	MHz	
SID250	F <sub>MAX-ADDER</sub>	Max frequency of 16-bit adder in a UDB pair	–	–	48	MHz	
SID251	F <sub>MAX_CRC</sub>	Max frequency of 16-bit CRC/PRS in a UDB pair	–	–	48	MHz	
<b>PLD Performance in UDB</b>							
SID252	F <sub>MAX_PLD</sub>	Max frequency of 2-pass PLD function in a UDB pair	–	–	48	MHz	
<b>Clock to Output Performance</b>							
SID253	T <sub>CLK_OUT_UBD1</sub>	Prop. delay for clock in to data out at 25 °C, Typ.	–	15	–	ns	
SID254	T <sub>CLK_OUT_UBD2</sub>	Prop. delay for clock in to data out, Worst case.	–	25	–	ns	

**Table 46. SIO Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
<b>SIO DC Specifications</b>							
SID330	V <sub>IH</sub>	Input voltage high threshold	0.7*VDD	–	–	V	CMOS input; with respect to V <sub>DDIO</sub>
SID331	V <sub>IL</sub>	Input voltage low threshold	–	–	0.3*VDD	V	CMOS input; with respect to V <sub>DDIO</sub>
SID332	V <sub>IH</sub>	Differential input mode high voltage; hysteresis disabled	V <sub>r</sub> +0.2	–	–	V	V <sub>r</sub> is the SIO reference voltage
SID333	V <sub>IL</sub>	Differential input mode low voltage; hysteresis disabled	–	–	V <sub>r</sub> -0.2	V	V <sub>r</sub> is the SIO reference voltage
SID334	V <sub>OH</sub>	Output high voltage in unregulated mode	VDDIO - 0.4	–	–	V	I <sub>OH</sub> = 4 mA, V <sub>DD</sub> = 3.3 V
SID335	V <sub>OH</sub>	Output high voltage in regulated mode	V <sub>r</sub> - 0.65	–	V <sub>r</sub> + 0.2	V	I <sub>OH</sub> = 1 mA
SID336	V <sub>OH</sub>	Output high voltage in regulated mode	V <sub>r</sub> - 0.3	–	V <sub>r</sub> + 0.2	V	I <sub>OH</sub> = 0.1 mA
SID337	V <sub>OL</sub>	Output low voltage	–	–	0.8	V	V <sub>DDIO</sub> = 3.3 V, I <sub>OL</sub> = 25 mA
SID338	V <sub>OL</sub>	Output low voltage	–	–	0.4	V	V <sub>DDIO</sub> = 1.8 V, I <sub>OL</sub> = 4 mA
SID339	V <sub>inref</sub>	Input voltage reference	0.48	–	0.52*VDDIO	V	
SID340	V <sub>outref</sub>	Output voltage reference (regulated mode)	1	–	VDDIO-1	V	V <sub>DDIO</sub> > 3.3
SID341	V <sub>outref</sub>	Output voltage reference (regulated mode)	1	–	VDDIO-0.5	V	V <sub>DDIO</sub> < 3.3
SID342	R <sub>PULLUP</sub>	Pull-up resistor	3.5	5.6	8.5	kΩ	
SID343	R <sub>PULLDOWN</sub>	Pull-down resistor	3.5	5.6	8.5	kΩ	
SID344	I <sub>IL</sub>	Input leakage current (absolute value)	–	–	14	nA	V <sub>IH</sub> ≤ V <sub>DDSIO</sub> ; 25 °C
SID345	I <sub>IL</sub>	Input leakage current (absolute value)	–	–	10	nA	V <sub>IH</sub> > V <sub>DDSIO</sub> ; 25 °C
SID346	C <sub>IN</sub>	Input capacitance	–	–	7	pF	
SID347	VHYST-Single	Hysteresis in single-ended mode	–	40	–	mV	
SID348	VHYST_Diff	Hysteresis in differential mode	–	35	–	mV	
SID349	I <sub>DIODE</sub>	Current through protection diode to V <sub>DD</sub> /V <sub>SS</sub>	–	–	100	μA	
<b>SIO AC Specifications (Guaranteed By Design)</b>							
SID350	T <sub>RISEF</sub>	Rise time in Fast Strong mode	–	–	12	ns	3.3-V V <sub>DD</sub> , C <sub>load</sub> = 25 pF
SID351	T <sub>FALLF</sub>	Fall time in Fast Strong mode	–	–	12	ns	3.3-V V <sub>DD</sub> , C <sub>load</sub> = 25 pF
SID352	T <sub>RISES</sub>	Rise time in Slow Strong mode	–	–	75	ns	3.3-V V <sub>DD</sub> , C <sub>load</sub> = 25 pF
SID353	T <sub>FALLS</sub>	Fall time in Slow Strong mode	–	–	70	ns	3.3-V V <sub>DD</sub> , C <sub>load</sub> = 25 pF
SID354	F <sub>SIOU1</sub>	SIO Fout; Unregulated, Fast Strong mode	–	–	33	MHz	3.3-V ≤ V <sub>DD</sub> ≤ 5.5 V, 25 pF. Guaranteed by design.
SID355	F <sub>SIOU2</sub>	SIO Fout; Unregulated, Fast Strong mode	–	–	16	MHz	1.71-V ≤ V <sub>DD</sub> ≤ 3.3 V, 25 pF
SID356	F <sub>SIOU3</sub>	SIO Fout; Regulated, Fast Strong mode	–	–	20	MHz	3.3-V ≤ V <sub>DD</sub> ≤ 5.5 V, 25 pF
SID357	F <sub>SIOU4</sub>	SIO Fout; Regulated, Fast Strong mode	–	–	10	MHz	1.71 V ≤ V <sub>DD</sub> ≤ 3.3 V, 25 pF

**Table 46. SIO Specifications** *(continued)*

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID358	F <sub>SIOOUT3</sub>	SIO Fout; Unregulated, Slow Strong mode.	–	–	5	MHz	3.3 V ≤ V <sub>DD</sub> ≤ 5.5 V, 25 pF
SID359	F <sub>SIOOUT4</sub>	SIO Fout, Unregulated, Slow Strong mode.	–	–	3.5	MHz	1.71 V ≤ V <sub>DD</sub> ≤ 3.3 V, 25 pF
SID360	F <sub>SIOOUT5</sub>	SIO Fout, Regulated, Slow Strong mode.	–	–	2.5	MHz	1.7 V ≤ V <sub>DD</sub> ≤ 5.5 V, 25 pF
SID361	F <sub>GPIOIN</sub>	GPIO input operating frequency; 1.71 V ≤ V <sub>DD</sub> ≤ 5.5 V	–	–	48	MHz	1.71 V ≤ V <sub>DD</sub> ≤ 5.5 V

**Table 47. CAN Specifications**

Spec ID#	Parameter	Description	Min	Typ	Max	Units	Details / Conditions
SID420	IDD_CAN	Block current consumption	–	–	200	uA	
SID421	CAN_bits	CAN Bit rate (Min 8-MHz clock)	–	–	1	Mbps	



## Ordering Information

The PSoC 4200-L family part numbers and features are listed in the following table.

**Table 48. PSoC 4200-L Ordering Information**

Category	MPN	Features														Package			
		Max CPU Speed (MHz)	Flash (KB)	SRAM (KB)	UDB	Op-amp (CTBm)	CSD	Direct LCD Drive	12-bit SAR ADC	LP Comparators	TCPWM Blocks	SCB Blocks	USB Full Speed	CAN	GPIO	48-TQFP	64-TQFP	68-QFN	124-VFBGA
4246	CY8C4246AZI-L423	48	64	8	8	2	1	✓	1000 ksps	2	8	3	–	–	38	✓	–	–	–
	CY8C4246AZI-L433	48	64	8	8	2	–	–	1000 ksps	2	8	3	✓	–	38	✓	–	–	–
	CY8C4246AZI-L435	48	64	8	8	2	–	–	1000 ksps	2	8	4	✓	–	53	–	✓	–	–
	CY8C4246AZI-L445	48	64	8	8	2	2	✓	1000 ksps	2	8	4	✓	–	53	–	✓	–	–
	CY8C4246LTI-L445	48	64	8	8	2	2	✓	1000 ksps	2	8	4	✓	–	57	–	–	✓	–
4247	CY8C4247AZI-L423	48	128	16	8	2	1	✓	1000 ksps	2	8	3	–	–	38	✓	–	–	–
	CY8C4247AZI-L433	48	128	16	8	2	–	–	1000 ksps	2	8	3	✓	–	38	✓	–	–	–
	CY8C4247AZI-L445	48	128	16	8	2	2	✓	1000 ksps	2	8	4	✓	–	53	–	✓	–	–
	CY8C4247LTI-L445	48	128	16	8	2	2	✓	1000 ksps	2	8	4	✓	–	57	–	–	✓	–
	CY8C4247AZI-L475	48	128	16	8	4	2	–	1000 ksps	2	8	4	✓	–	53	–	✓	–	–
	CY8C4247LTI-L475	48	128	16	8	4	2	–	1000 ksps	2	8	4	✓	–	57	–	–	✓	–
	CY8C4247BZI-L479	48	128	16	8	4	2	–	1000 ksps	2	8	4	✓	–	98	–	–	–	✓
	CY8C4247AZI-L485	48	128	16	8	4	2	✓	1000 ksps	2	8	4	✓	✓	53	–	✓	–	–
	CY8C4247LTI-L485	48	128	16	8	4	2	✓	1000 ksps	2	8	4	✓	✓	57	–	–	✓	–
	CY8C4247BZI-L489	48	128	16	8	4	2	✓	1000 ksps	2	8	4	✓	✓	98	–	–	–	✓
4248	CY8C4248BZI-L469	48	256	32	8	4	–	–	1000 ksps	2	8	4	–	–	96	–	–	–	✓
	CY8C4248AZI-L475	48	256	32	8	4	2	–	1000 ksps	2	8	4	✓	–	53	–	✓	–	–
	CY8C4248LTI-L475	48	256	32	8	4	2	–	1000 ksps	2	8	4	✓	–	57	–	–	✓	–
	CY8C4248BZI-L479	48	256	32	8	4	2	–	1000 ksps	2	8	4	✓	–	98	–	–	–	✓
	CY8C4248AZI-L485	48	256	32	8	4	2	✓	1000 ksps	2	8	4	✓	✓	53	–	✓	–	–
	CY8C4248LTI-L485	48	256	32	8	4	2	✓	1000 ksps	2	8	4	✓	✓	57	–	–	✓	–
	CY8C4248BZI-L489	48	256	32	8	4	2	✓	1000 ksps	2	8	4	✓	✓	98	–	–	–	✓

**Table 52. Acronyms Used in this Document** *(continued)*

Acronym	Description
PC	program counter
PCB	printed circuit board
PGA	programmable gain amplifier
PHUB	peripheral hub
PHY	physical layer
PICU	port interrupt control unit
PLA	programmable logic array
PLD	programmable logic device, see also PAL
PLL	phase-locked loop
PMDD	package material declaration data sheet
POR	power-on reset
PRES	precise power-on reset
PRS	pseudo random sequence
PS	port read data register
PSoC®	Programmable System-on-Chip™
PSRR	power supply rejection ratio
PWM	pulse-width modulator
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
RTC	real-time clock
RTL	register transfer language
RTR	remote transmission request
RX	receive
SAR	successive approximation register
SC/CT	switched capacitor/continuous time
SCL	I <sup>2</sup> C serial clock
SDA	I <sup>2</sup> C serial data
S/H	sample and hold
SINAD	signal to noise and distortion ratio
SIO	special input/output, GPIO with advanced features. See GPIO.
SOC	start of conversion
SOF	start of frame
SPI	Serial Peripheral Interface, a communications protocol
SR	slew rate
SRAM	static random access memory
SRES	software reset
SWD	serial wire debug, a test protocol

**Table 52. Acronyms Used in this Document** *(continued)*

Acronym	Description
SWV	single-wire viewer
TD	transaction descriptor, see also DMA
THD	total harmonic distortion
TIA	transimpedance amplifier
TRM	technical reference manual
TTL	transistor-transistor logic
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
UDB	universal digital block
USB	Universal Serial Bus
USBIO	USB input/output, PSoC pins used to connect to a USB port
VDAC	voltage DAC, see also DAC, IDAC
WDT	watchdog timer
WOL	write once latch, see also NVL
WRES	watchdog timer reset
XRES	external reset I/O pin
XTAL	crystal

## Document Conventions

### Units of Measure

**Table 53. Units of Measure**

Symbol	Unit of Measure
°C	degrees Celsius
dB	decibel
fF	femto farad
Hz	hertz
KB	1024 bytes
kbps	kilobits per second
Khr	kilohour
kHz	kilohertz
kΩ	kilo ohm
ksps	kilosamples per second
LSB	least significant bit
Mbps	megabits per second
MHz	megahertz
MΩ	mega-ohm
Msps	megasamples per second
μA	microampere
μF	microfarad
μH	microhenry
μs	microsecond
μV	microvolt
μW	microwatt
mA	milliampere
ms	millisecond
mV	millivolt
nA	nanoampere
ns	nanosecond
nV	nanovolt
Ω	ohm
pF	picofarad
ppm	parts per million
ps	picosecond
s	second
sps	samples per second
sqrtHz	square root of hertz
V	volt

## Revision History

Description Title: PSoC® 4: PSoC 4200-L Family Datasheet Programmable System-on-Chip (PSoC®) Document Number: 001-91686				
Revision	ECN	Orig. of Change	Submission Date	Description of Change
**	4414601	WKA	02/06/2015	New datasheet for new device family.
*A	4774497	WKA	05/22/2015	Updated Pin List. Added a footnote explaining ground perturbations in <a href="#">GPIO AC Specifications</a> . Updated values for SID269, SID270, SID271, and SID291. Added Conditions for Deep Sleep Mode in <a href="#">Opamp Specifications</a> . Updated Conditions for SID_DS_10 through SID_DS_18. Added Conditions for SID_DS_22 through SID_DS_24. Updated description for SID85 and SID85A. Updated values for SID89, SID248, SID259, SID91, SID258, and SID92. Updated max value for SID.TCPWM.2A. Updated typ and max values for SID149. Added <a href="#">PLL DC Specifications</a> and <a href="#">PLL AC Specifications</a> . Updated <a href="#">Watch Crystal Oscillator (WCO) Specifications</a> . Added <a href="#">CAN Specifications</a> . Changed µFBGA package to VFBGA package.
*B	4867142	WKA	08/03/2015	Changed datasheet status to Preliminary. Updated <a href="#">Pinouts</a> . Removed typ value for SID43. Updated Conditions for SID_DS_7, SID_DS_8, and SID_DS_9. Updated max value for SID87. Removed SID179. Added <a href="#">External Crystal Oscillator (ECO) Specifications</a> . Updated max value for SID321, SID353, and SID359. Added "Guaranteed by Design" note for SID354. Updated <a href="#">Ordering Information</a> .
*C	5034067	WKA	12/03/2015	Updated Conditions for SID85A, SID247A, SID259, SID92, SID417, SID416A Updated typ and max values for SID410. Updated description for SID323. Added "Guaranteed by Characterization" note for SIO AC Specs. Updated <a href="#">Ordering Information</a> .
*D	5170871	WKA	03/11/2016	Removed VDDA and VDDIO pins in <a href="#">Regulated External Supply</a> section. Updated values for Deep Sleep Mode, Hibernate Mode and Stop Mode in <a href="#">DC Specifications</a> . Added SID299A. Added a note in <a href="#">UDB Port Adaptor Specifications</a> that all specs except TLCLKDO are guaranteed by design. Updated T <sub>JA</sub> value for the 124-VFBGA package.
*E	5281150	WKA	05/23/2016	Changed datasheet status to Final. Updated max values for SID6, SID7, SID8, SID9, SID31, SID32, SID34, SID35, SID40, SID41, SID43, and SID44. Updated the template.
*F	5516529	WKA	11/15/2016	Added CY8C4248BZI-L469 in <a href="#">Ordering Information</a> .
*G	5559970	WKA	11/20/2016	Updated max values for SID33, SID34, and SID35. Updated SID171.

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